

Cleaning Wafer Substrates



SPI Supplies
206 Garfield Avenue,
West Chester, PA 19380, USA

Preparation of Wafer Substrates

Cleaning Substrate Surfaces

There are many methods for cleaning substrate materials; much depends on the intended application as well as the level of cleanliness desired. Here are a couple of suggestions.



One common method is to place the wafer in acetone and use an [ultrasonic cleaner](#) for some period of time (typically 5 to 15 minutes). Immediately after removal, rinse with ethanol and/or methanol and dried with a dry N2 gun, or a compressed [air can](#). When using this method, you must watch for residue left on the surface by the solvents

- this can be an issue.



For many surface, the use of the [Plasma Prep III](#) will easily remove organics in an O2 environment. Other gasses can be used for different cleaning applications.

For [spin-coating](#) applications, adding a few drops of a strong solvent (such as 2-methoxyethanol) onto the wafer using a syringe. Then spin the wafer to remove the excess solvent, followed by drying on a hot plate to remove any remaining organics.



Do you have a favorite method? [Please let us know](#) and we will acknowledge and add you to our suggested preparations!

EER 12-18